Both for laser and iron tip soldering

LEAD-FREE SOLDER EVASOL 鉛フリーはんだ エバソル

EVASOL MYK SERIES

Higher reliability for automotive device
Good outlook with Transparent flux residue

Can apply with laser soldering with low Ag

Good wettability with low Ag alloy can help to reduce cost.

Very few spattering

Select suitable flux base material for higher melting point alloy. Very few flux spattering can achieve high performance soldering.

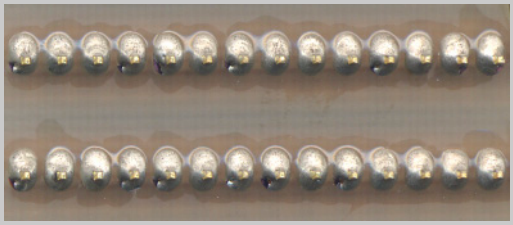
Transparent flux residue

Good for after soldering appearance with transparent flux such as LED illumination.

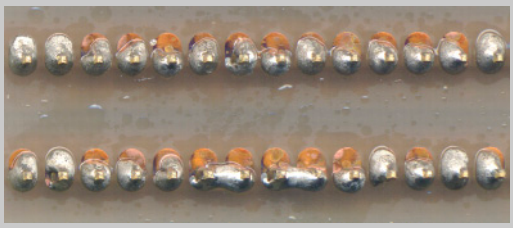
Can apply with light beam soldering with low Ag

●Confirmation of wettability with light beam soldering

R4-MYK-3 (Sn0.3Ag0.7Cu) Wetting ratio 98.3%



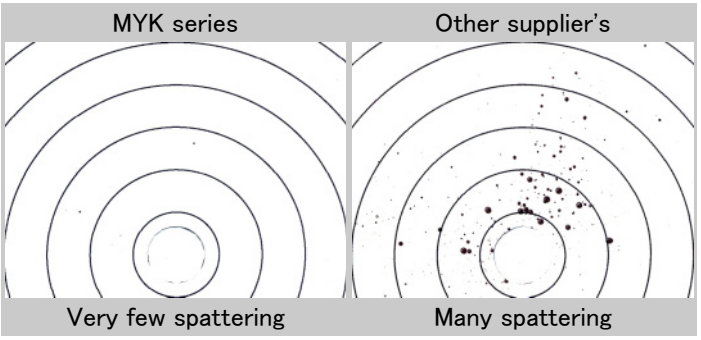
Other supplier's (Sn-3Ag-0.5Cu) Wetting ratio 63.0%



【Condition】 Beam power：40W　Wire diameter：Φ0.8mm
Preheat：0.05s　Wire feed：7mm/s,1.6s
Postheating：0.3s　PCB：Cu, one side
Connector terminal：Brass, Sn plating on Ni

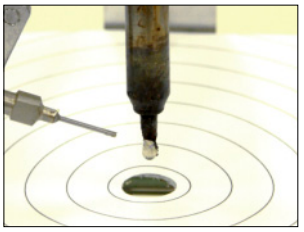
Very few spattering

●Flux spattering test by using soldering iron robot



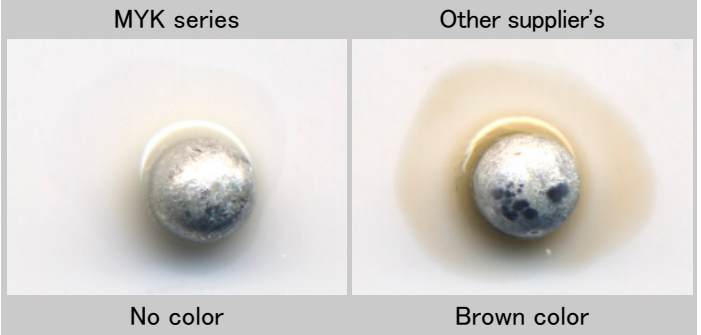
Collect spattered flux onto thermal paper.

【Condition】
Iron temp. ： 380℃
Feed speed ： 25mm/s
Feed length：5mm × 200 shots



Good outlook after soldering

●Put solder wire on white ceramic plate and heat with 270℃



Can achieve higher productivity for outlook inspection

Characteristics

Test items	Characteristics		Test method
Alloy type	J3 R4	Sn-Ag3.0-Cu0.5 Sn-Ag0.3-Cu0.7	—
Flux type	JIS-A, MIL-RMA		—
Flux contents (%)	3.0, 4.0, 6.0		IPC TM650 2.3.34.1
Halide contents (%)	0.08～0.14		IPC TM650 2.3.35
Flux solution resistivity(Ωm)	More than 1000		MIL QQ-S-571F
Copper plate corrosion	No corrosion		IPC TM650 2.6.15
Copper mirror corrosion	No corrosion		IPC TM650 2.3.32
Insulation resistance (Ω)	More than 5.0×10^8		IPC TM650 2.6.3.3 IPC TM650 2.6.14.1 (85℃ 85%RH)
Electrochemical migration	No migration		

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